

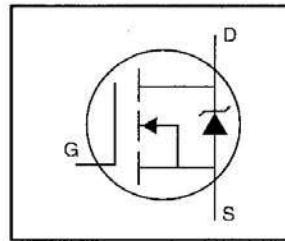
International **IR** Rectifier

PD - 94943

IRFZ44PbF

HEXFET® Power MOSFET

- Dynamic dv/dt Rating
- 175°C Operating Temperature
- Fast Switching
- Ease of Parallelizing
- Simple Drive Requirements
- Lead-Free

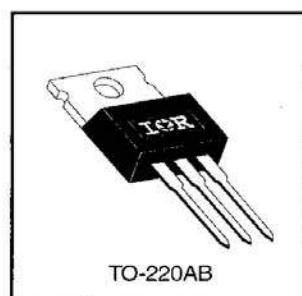


$V_{DSS} = 60V$
 $R_{DS(on)} = 0.028\Omega$
 $I_D = 50^*A$

Description

Third Generation HEXFETs from International Rectifier provide the designer with the best combination of fast switching, ruggedized device design, low on-resistance and cost-effectiveness.

The TO-220 package is universally preferred for all commercial-industrial applications at power dissipation levels to approximately 50 watts. The low thermal resistance and low package cost of the TO-220 contribute to its wide acceptance throughout the industry.



Absolute Maximum Ratings

	Parameter	Max.	Units
$I_D @ T_c = 25^\circ C$	Continuous Drain Current, $V_{GS} @ 10 V$	50*	A
$I_D @ T_c = 100^\circ C$	Continuous Drain Current, $V_{GS} @ 10 V$	36	
I_{DM}	Pulsed Drain Current ①	200	
$P_D @ T_c = 25^\circ C$	Power Dissipation	150	W
	Linear Derating Factor	1.0	W/ $^\circ C$
V_{GS}	Gate-to-Source Voltage	± 20	V
E_{AS}	Single Pulse Avalanche Energy ②	100	mJ
dv/dt	Peak Diode Recovery dv/dt ③	4.5	V/ns
T_J T_{STG}	Operating Junction and Storage Temperature Range	-55 to +175	$^\circ C$
	Soldering Temperature, for 10 seconds	300 (1.6mm from case)	
	Mounting Torque, 6-32 or M3 screw	10 lbf-in (1.1 N·m)	

Thermal Resistance

	Parameter	Min.	Typ.	Max.	Units
R_{JC}	Junction-to-Case	—	—	1.0	$^\circ C/W$
R_{CS}	Case-to-Sink, Flat, Greased Surface	—	0.50	—	
R_{JA}	Junction-to-Ambient	—	—	62	

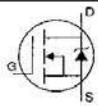
IRFZ44PbF

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Electrical Characteristics @ $T_J = 25^\circ\text{C}$ (unless otherwise specified)

	Parameter	Min.	Typ.	Max.	Units	Test Conditions
$V_{(\text{BR})\text{DSS}}$	Drain-to-Source Breakdown Voltage	60	—	—	V	$V_{\text{GS}}=0\text{V}$, $I_D=250\mu\text{A}$
$\Delta V_{(\text{BR})\text{DSS}/\Delta T_J}$	Breakdown Voltage Temp. Coefficient	—	0.060	—	V/ $^\circ\text{C}$	Reference to 25°C , $I_D=1\text{mA}$
$R_{\text{DS}(\text{on})}$	Static Drain-to-Source On-Resistance	—	—	0.028	Ω	$V_{\text{GS}}=10\text{V}$, $I_D=31\text{A}$ ④
$V_{\text{GS}(\text{th})}$	Gate Threshold Voltage	2.0	—	4.0	V	$V_{\text{DS}}=V_{\text{GS}}$, $I_D=250\mu\text{A}$
g_{fs}	Forward Transconductance	15	—	—	S	$V_{\text{DS}}=25\text{V}$, $I_D=31\text{A}$ ④
I_{DS}	Drain-to-Source Leakage Current	—	—	25	μA	$V_{\text{DS}}=60\text{V}$, $V_{\text{GS}}=0\text{V}$
		—	—	250		$V_{\text{DS}}=48\text{V}$, $V_{\text{GS}}=0\text{V}$, $T_J=150^\circ\text{C}$
I_{GSS}	Gate-to-Source Forward Leakage	—	—	100	nA	$V_{\text{GS}}=20\text{V}$
	Gate-to-Source Reverse Leakage	—	—	-100		$V_{\text{GS}}=-20\text{V}$
Q_g	Total Gate Charge	—	—	67	nC	$I_D=51\text{A}$
Q_{gs}	Gate-to-Source Charge	—	—	18		$V_{\text{DS}}=48\text{V}$
Q_{gd}	Gate-to-Drain ("Miller") Charge	—	—	25		$V_{\text{GS}}=10\text{V}$ See Fig. 6 and 13 ④
$t_{\text{d(on)}}$	Turn-On Delay Time	—	14	—	ns	$V_{\text{DD}}=30\text{V}$
t_r	Rise Time	—	110	—		$I_D=51\text{A}$
$t_{\text{d(off)}}$	Turn-Off Delay Time	—	45	—		$R_G=9.1\Omega$
t_f	Fall Time	—	92	—		$R_D=0.55\Omega$ See Figure 10 ④
L_D	Internal Drain Inductance	—	4.5	—	nH	Between lead, 6 mm (0.25in.) from package and center of die contact
L_S	Internal Source Inductance	—	7.5	—		
C_{iss}	Input Capacitance	—	1900	—	pF	$V_{\text{GS}}=0\text{V}$
C_{oss}	Output Capacitance	—	920	—		$V_{\text{DS}}=25\text{V}$
C_{rss}	Reverse Transfer Capacitance	—	170	—		$f=1.0\text{MHz}$ See Figure 5

Source-Drain Ratings and Characteristics

	Parameter	Min.	Typ.	Max.	Units	Test Conditions
I_S	Continuous Source Current (Body Diode)	—	—	50*	A	MOSFET symbol showing the integral reverse p-n junction diode. 
I_{SM}	Pulsed Source Current (Body Diode) ①	—	—	200		
V_{SD}	Diode Forward Voltage	—	—	2.5		$T_J=25^\circ\text{C}$, $I_S=51\text{A}$, $V_{\text{GS}}=0\text{V}$ ④
t_{rr}	Reverse Recovery Time	—	120	180	ns	$T_J=25^\circ\text{C}$, $I_F=51\text{A}$ $dI/dt=100\text{A}/\mu\text{s}$ ④
Q_{rr}	Reverse Recovery Charge	—	0.53	0.80	μC	
t_{on}	Forward Turn-On Time	Intrinsic turn-on time is negligible (turn-on is dominated by L_S+L_D)				

Notes:

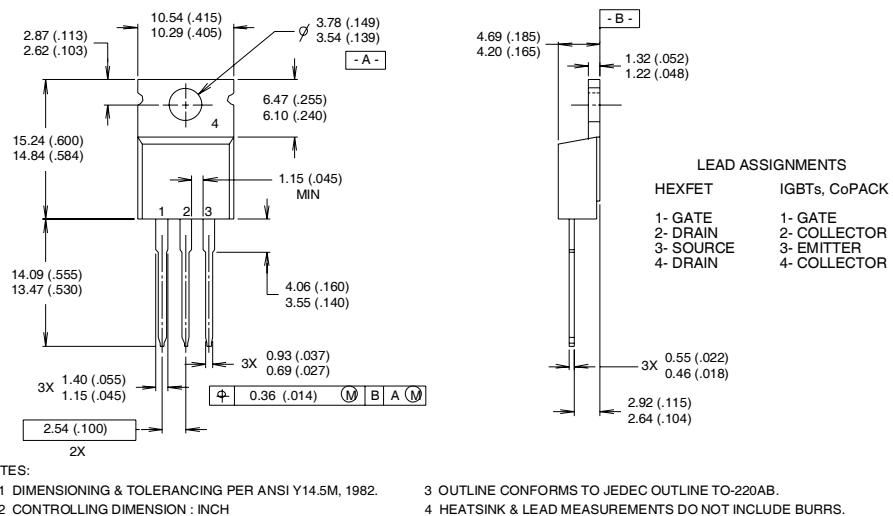
① Repetitive rating; pulse width limited by max. junction temperature (See Figure 11) ③ $I_{\text{SD}} \leq 51\text{A}$, $di/dt \leq 250\text{A}/\mu\text{s}$, $V_{\text{DD}} \leq V_{(\text{BR})\text{DSS}}$, $T_J \leq 175^\circ\text{C}$

② $V_{\text{DD}}=25\text{V}$, starting $T_J=25^\circ\text{C}$, $L=44\mu\text{H}$, $R_G=25\Omega$, $I_A=51\text{A}$ (See Figure 12) ④ Pulse width $\leq 300\ \mu\text{s}$; duty cycle $\leq 2\%$.

* Current limited by the package, (Die Current = 51A)

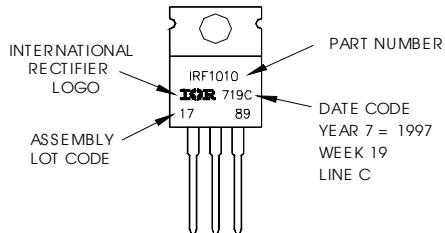
TO-220AB Package Outline

Dimensions are shown in millimeters (inches)



TO-220AB Part Marking Information

EXAMPLE: THIS IS AN IRF1010
LOT CODE 1789
ASSEMBLED ON WW 19, 1997
IN THE ASSEMBLY LINE "C"
Note: "P" in assembly line
position indicates "Lead-Free"



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